



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

# PRINTED CIRCUIT BOARDS

01

4.11.2001

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## Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 172 FR4 70 L36.70 P18

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_172\_FR4\_70\_L36.70\_p18

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	70 $\mu$	Copper	 (180 $\mu$ PrePreg-Type: 7628)	
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-2	70 $\mu$	Copper		
	360 $\mu$	L-FR4		
Layer-3	70 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-99	70 $\mu$	Copper		

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